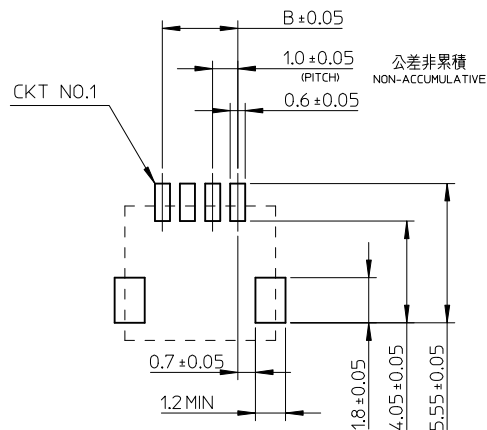
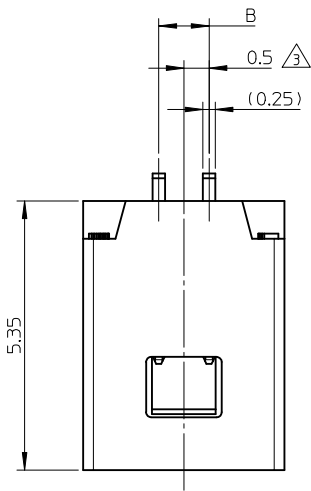
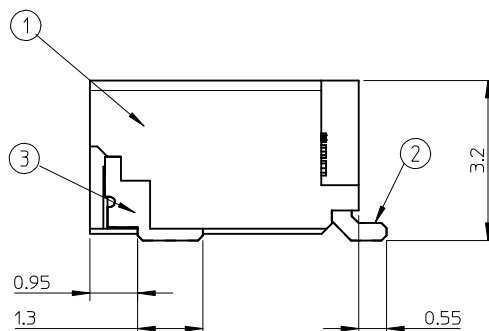
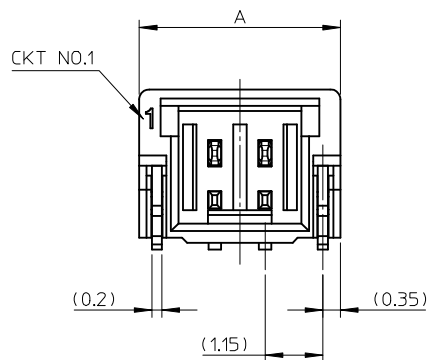




参考パターンレイアウト
RECOMMENDED PATTERN DIM.(REF)
SCALE:5-1



NOTES

1. かん合相手 : 501330-****
MATE WITH : 501330-****
2. ソルダーピン及びネールの平坦度は0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
3. 極数 = 偶数に適用
APPLY FOR CKT SIZE=EVEN
4. 6~15極は、SD-501568-002を参照下さい。
REFER TO SD-501568-002 ABOUT 6-15CKT.

番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	耐熱ナイロン、UL94V-0、色：自然色 HEAT RESISTANCE NYLON, UL94V-0, COLOR:NATURAL
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING
③	ネイル NAIL	黄銅 BRASS すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING

4.0	7.0	501568-0507	5	501568-***07
3.0	6.0	501568-0407	4	
2.0	5.0	501568-0307	3	
1.0	4.0	501568-0207	2	
B	A	MATERIAL NO.	CKT	MODEL NO.

REVISED EC NO: J2014-1558 DRAWN:RHORI CHKD:KASAKAWA APPR:NUKITA 2014/04/15 2014/04/15 2014/04/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY AMIZUMURA	DATE 2005/01/19	TITLE 1.0 WIRE TO BOARD CONN. 1-ROW R/A WAFER ASSY 2-5CKT -LEAD FREE- molex				
		10 OVER 30 UNDER	± 0.25	CHECKED BY MYAGI	DATE 2005/01/19					
		30 OVER	± 0.3	APPROVED BY ANODA	DATE 2005/01/19					
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SD-501568-001		1 OF 2		
	REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10

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8

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6

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4

3

2

1

F

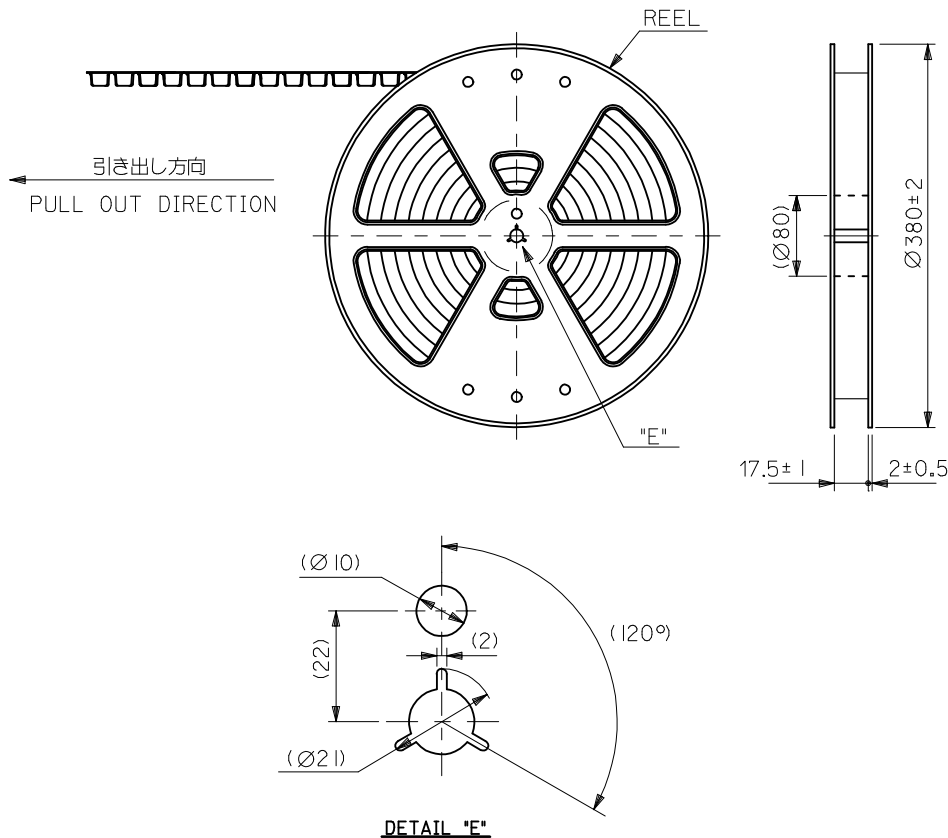
E

D

C

B

A

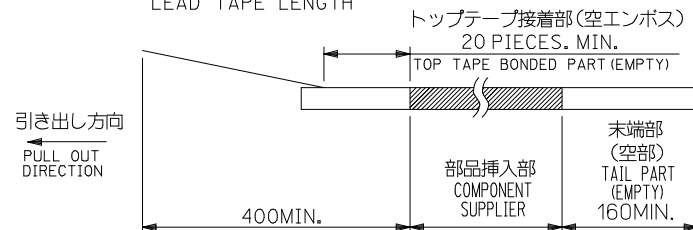


NOTES

1. 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE
THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).

2. 梱包数量 : 1700 個/リール
NUMBER OF CONNECTORS : 1700PIECES/REEL

3. リードテープ長さ
LEAD TAPE LENGTH



4. 材料

MATERIAL

キャリアテープ : ポリプロピレン

CARRIER TAPE : POLYPROPYLENE

トップテープ : PET、PE、REF

TOP TAPE

リール : ポリスチレン<リサイクル材を含む>

REEL : POLYSTYRENE <RECYCLE MATERIAL CONTAINED>

5. ELV及びRoHS適合品。

ELV AND RoHS COMPLIANT.

6. 本製品は乾燥剤入り、ハイバリア梱包仕様である。

(501568-0607~1507以外)

THIS PRODUCT IS HIGH BARRIER PACKAGE
WITH DESICCANT.

(BESIDES 501568-0607~1507)

REVISED	EC NO: J2014-1558	2014/04/15	2014/04/16	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
					10 UNDER	± 0.2	DRAWN BY	DATE	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTB PKG				
					10 OVER 30 UNDER	± 0.25	CHECKED BY	DATE					
					30 OVER	± 0.3	APPROVED BY	DATE	molex				
					ANGULAR ±1 °		ANODA 2005/1/26						
					DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.						
		SEE SHEET 2,3		SD-501568-005		1 OF 3							
C				REV		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

9

8

7

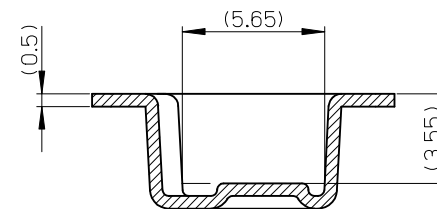
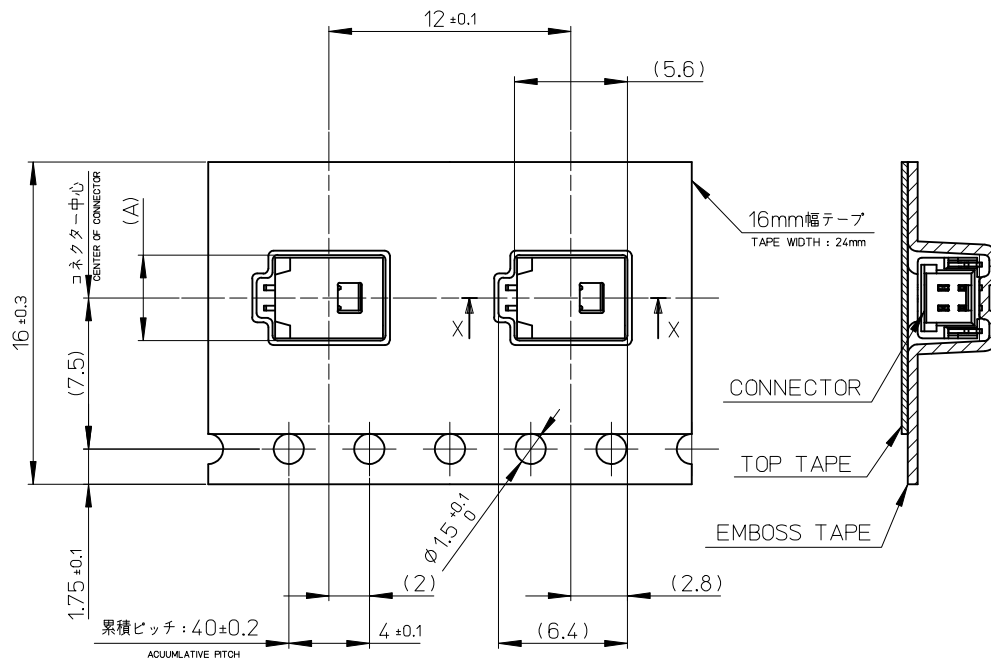
6

5

4

3

2



SECT.X-X
SCALE:4-1

7.3	501568-0507	5
6.3	501568-0407	4
5.3	501568-0307	3
4.3	501568-0207	2
(A)	MATERIAL NO.	CKTS.

REVISED EC NO: J2014-1558 DRWN:RHORI CHKD: APPR:NUKITA	DESCRIPTION 2014/04/15 2014/04/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY AMIZUMURA	DATE 2005/1/26	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW R/A) EMBTP PKG				
		10 OVER 30 UNDER	± 0.25	CHECKED BY MYAGI	DATE 2005/1/26					
		30 OVER	± 0.3	APPROVED BY ANODA	DATE 2005/1/26	DOCUMENT NO. SD-501568-005				
		ANGULAR ±3 °		MATERIAL NO.						
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART						
		REV	SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

